



Material Content Data Sheet



Sales Product Name		BSC014NE2LSI		Issued		2. August 2019		
MA#		MA005345237						
Package		PG-TDSON-8-50		Weight*		106.40 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.732	0.69	0.69	6884	6884
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		128	
	non noble metal	zinc	7440-66-6	0.055	0.05		512	
	non noble metal	iron	7439-89-6	1.090	1.02		10247	
wire	non noble metal	copper	7440-50-8	44.271	41.61	42.69	416089	426976
	noble metal	gold	7440-57-5	0.042	0.04	0.04	396	396
encapsulation	organic material	carbon black	1333-86-4	0.085	0.08		800	
	plastics	epoxy resin	-	3.916	3.68		36802	
	inorganic material	silicondioxide	60676-86-0	38.560	36.24	40.00	362416	400018
leadfinish	non noble metal	tin	7440-31-5	1.264	1.19	1.19	11877	11877
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	273	273
solder	noble metal	silver	7440-22-4	0.025	0.02		240	
	non noble metal	tin	7440-31-5	0.051	0.05		479	
	non noble metal	lead	7439-92-1	0.943	0.89	0.96	8865	9584
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		43	
	non noble metal	zinc	7440-66-6	0.018	0.02		173	
	non noble metal	iron	7439-89-6	0.368	0.35		3456	
	non noble metal	copper	7440-50-8	14.930	14.03	14.40	140320	143992
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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